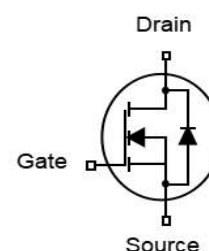


## Features

- Super-Junction MOSFET
- Low ON Resistance
- Improved dv/dt Capability
- 100% Avalanche Tested
- RoHS compliant
- 100% EAS Tested

$V_{DS}$	650	V
$R_{DS(on),TYP}@ V_{GS}=10V$	520	m $\Omega$
$I_D$	8	A

**TO-252**


Part ID	Package Type	Marking	Packing
ZT65T520D	TO-252	ZT65T520D	2500pcs/Reel

## Absolute Maximum Ratings $T_A=25^{\circ}\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating	Unit	
<b>Common Ratings (<math>T_c=25^{\circ}\text{C}</math> Unless Otherwise Noted)</b>				
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	650	V	
$T_J$	Maximum Junction Temperature	150	$^{\circ}\text{C}$	
$T_{STG}$	Storage Temperature Range	-55 to 150	$^{\circ}\text{C}$	
$I_{DM}$	Drain Current-Continuous@ Current-Pulsed (Note 2)	$T_c=25^{\circ}\text{C}$ 24	A	
<b>Mounted on Large Heat Sink</b>				
$I_D$	Drain Current-Continuous (Note 1)	$T_c=25^{\circ}\text{C}$	8	A
		$T_c=100^{\circ}\text{C}$	4.8	A
$P_D$	Maximum Power Dissipation	104	W	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.2	$^{\circ}\text{C}/\text{W}$	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	98	$^{\circ}\text{C}/\text{W}$	
<b>Drain-Source Avalanche Ratings</b>				
EAS	Avalanche Energy, Single Pulsed (Note 3)	122	mJ	
dv/dt	MOSFET dv/dt Ruggedness( $V_{DS}=0\sim 400\text{V}$ )	50	mJ	
dv/dt	Reverse Diode dv/dt (Note 4)	15	V/ns	

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ T<sub>J</sub>=25°C (unless otherwise stated)</b>						
V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	650	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V	--	--	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.8	3.3	3.8	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =4A	--	520	580	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, f=1MHz	--	465	--	pF
C <sub>oss</sub>	Output Capacitance		--	22	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	0.9	--	pF
R <sub>g</sub>	Gate Resistance	f=1MHz	--	14	--	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =325V, I <sub>D</sub> =8A, V <sub>GS</sub> =10V	--	11.2	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	2.46	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	4.66	--	nC
<b>Switching Characteristics</b>						
T <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =325V, I <sub>D</sub> =8A, R <sub>G</sub> =25Ω, V <sub>GS</sub> =10V	--	15.2	--	ns
T <sub>r</sub>	Turn-on Rise Time		--	18	--	ns
T <sub>d(off)</sub>	Turn-Off Delay Time		--	60.3	--	ns
T <sub>f</sub>	Turn-Off Fall Time		--	16.8	--	ns
<b>Source- Drain Diode Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
V <sub>SD</sub>	Forward on voltage	I <sub>S</sub> =8A, V <sub>GS</sub> =0V	--	--	1.3	V
T <sub>rr</sub>	Reverse Recovery Time	T <sub>J</sub> =25°C, I <sub>S</sub> =8A, V <sub>GS</sub> =0V di/dt=100A/μs	--	211	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	1.75	--	μC

**Notes:**

1. Drain current is limited by maximum junction temperature.
2. Repetitive rating : pulse width limited by junction temperature.
3. L = 60mH, I<sub>AS</sub> = 2A, V<sub>DD</sub> = 50V, R<sub>G</sub>=25Ω, Starting at T<sub>J</sub> = 25°C
4. I<sub>SD</sub> ≤ I<sub>D</sub>, di/dt = 100A/us, V<sub>DD</sub> ≤ 400V, Starting at T<sub>J</sub> = 25°C

Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

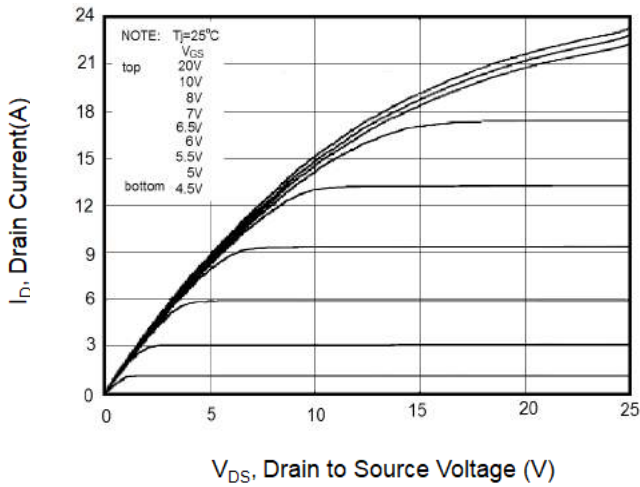


Fig1. Output characteristics

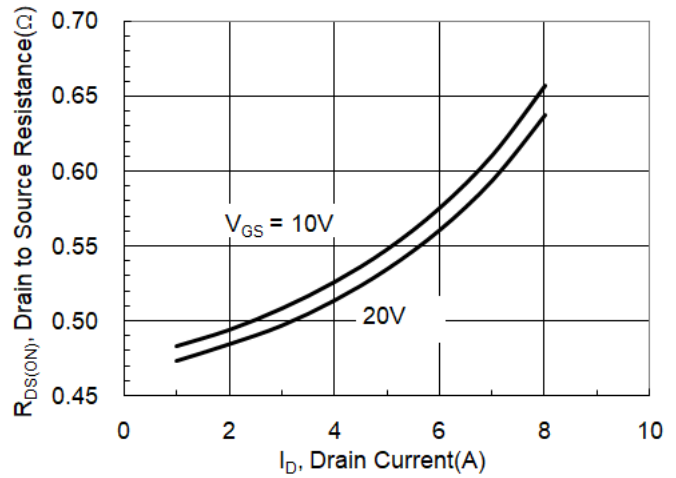


Fig4. Drain-source on-state resistance

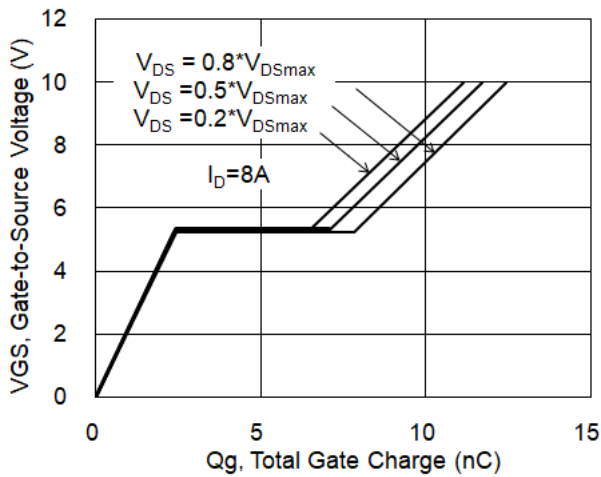


Fig2. Gate charge characteristics

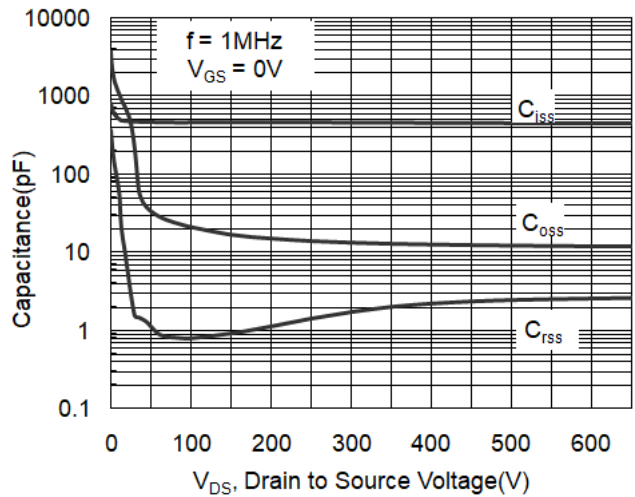


Fig5. Capacitance Characteristics

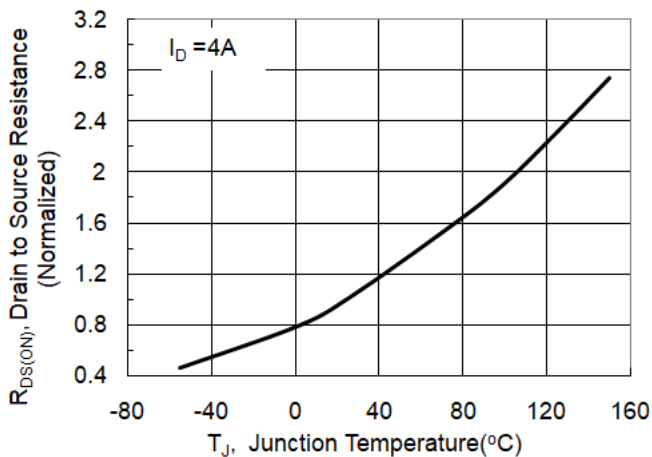


Fig3.  $R_{DS(ON)}$  vs junction temperature

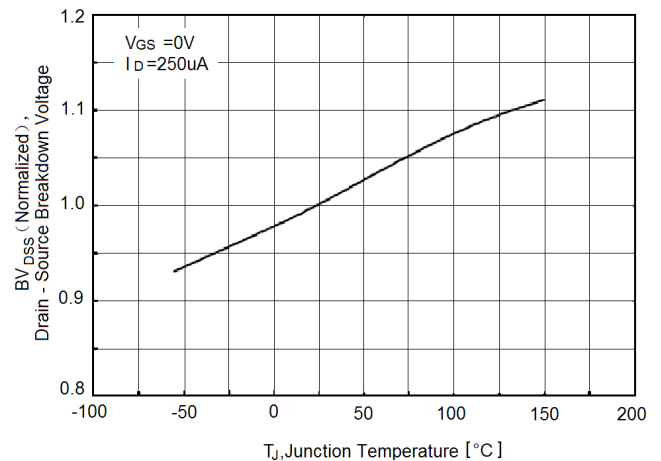


Fig6.  $BV_{DSS}$  vs junction temperature

Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

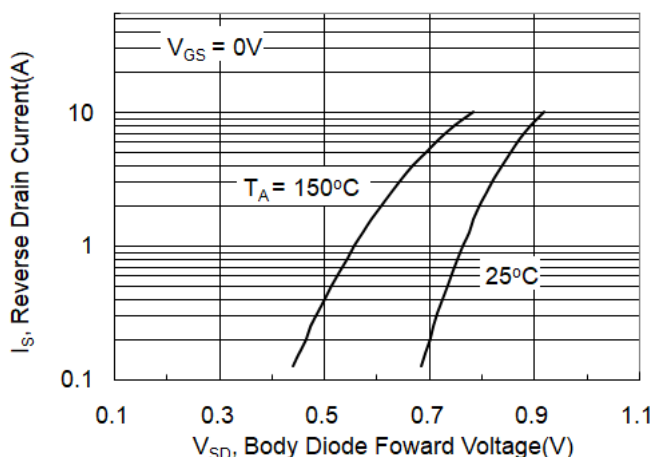


Fig 7 . Forward characteristics of reverse diode

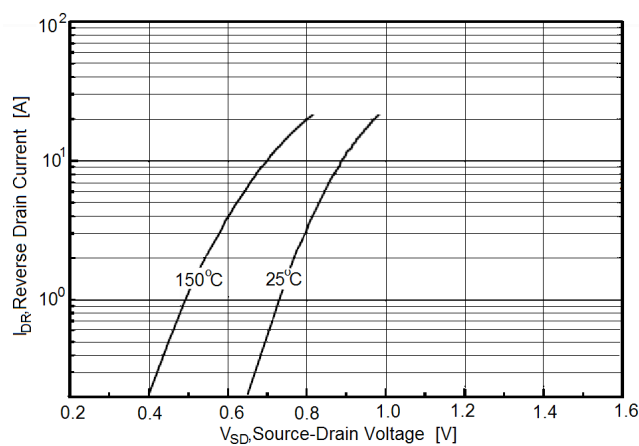


Fig 9 . Transfer characteristics

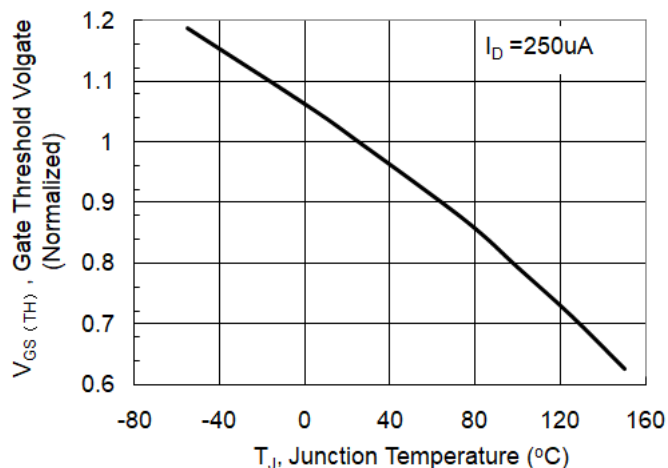


Fig 8 .  $V_{GS(TH)}$  vs junction temperature

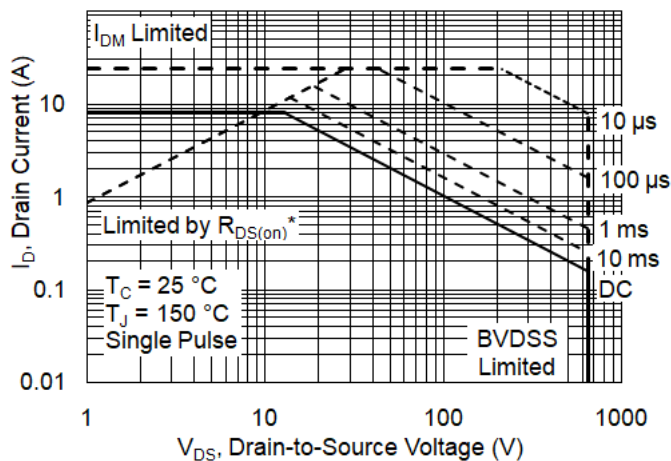


Fig 10. Safe operating area(TO-252)

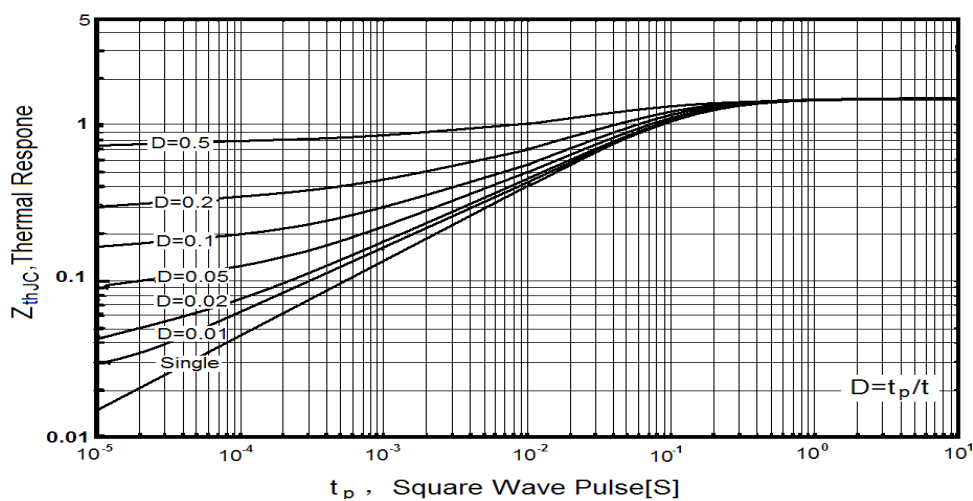


Fig 11. Transient thermal impedance (TO-252)

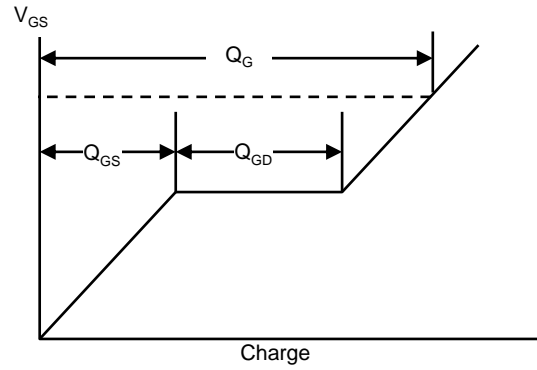
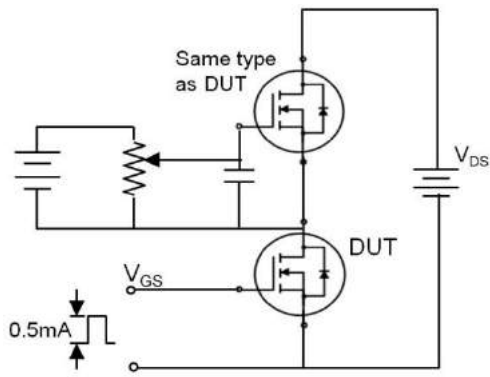


Fig A. Gate charge test circuit & waveform

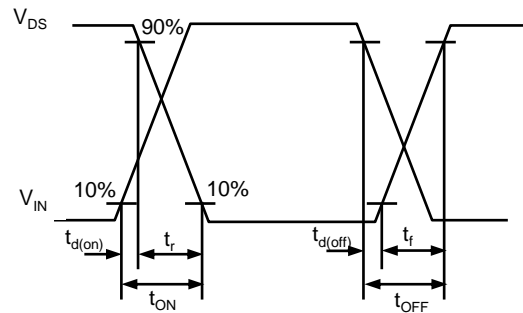
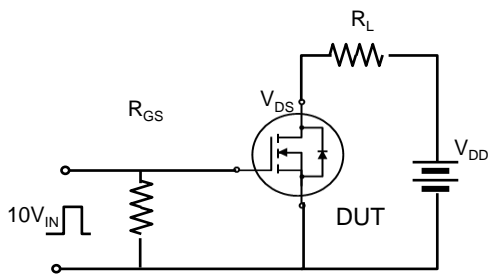


Fig B. Switching time test circuit & waveform

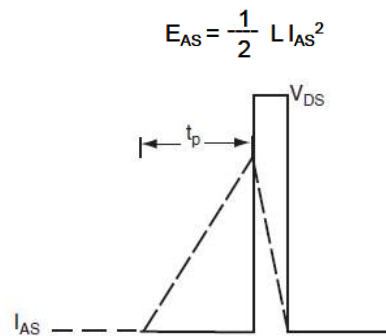
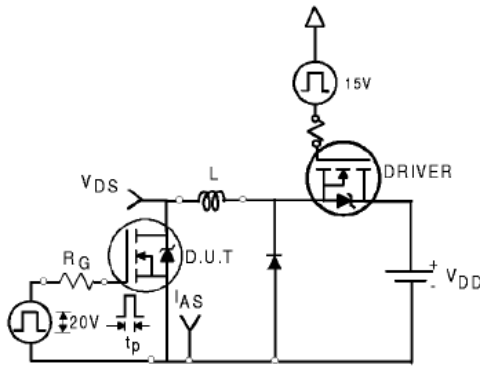
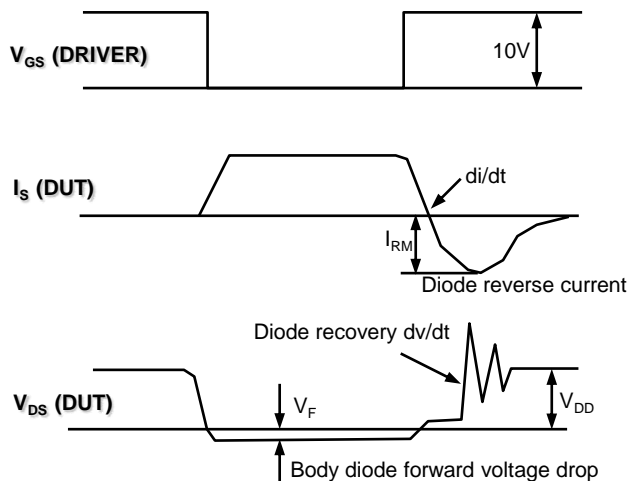
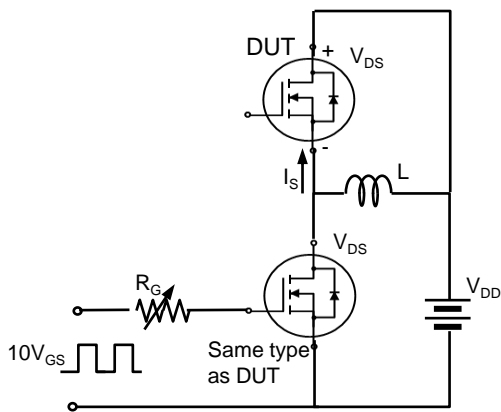


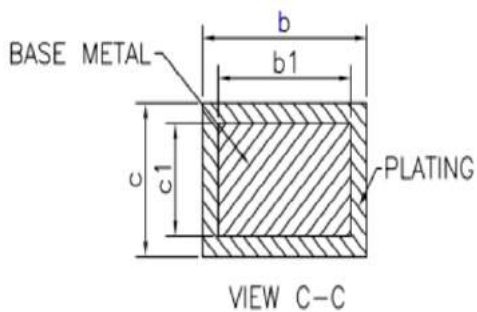
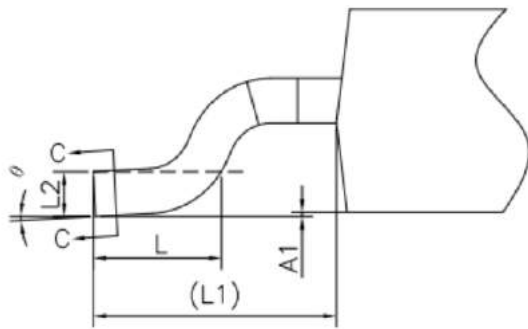
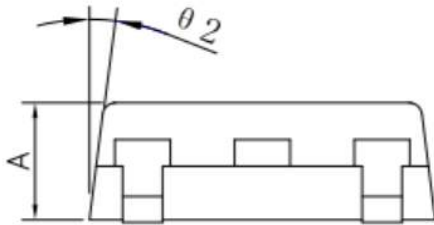
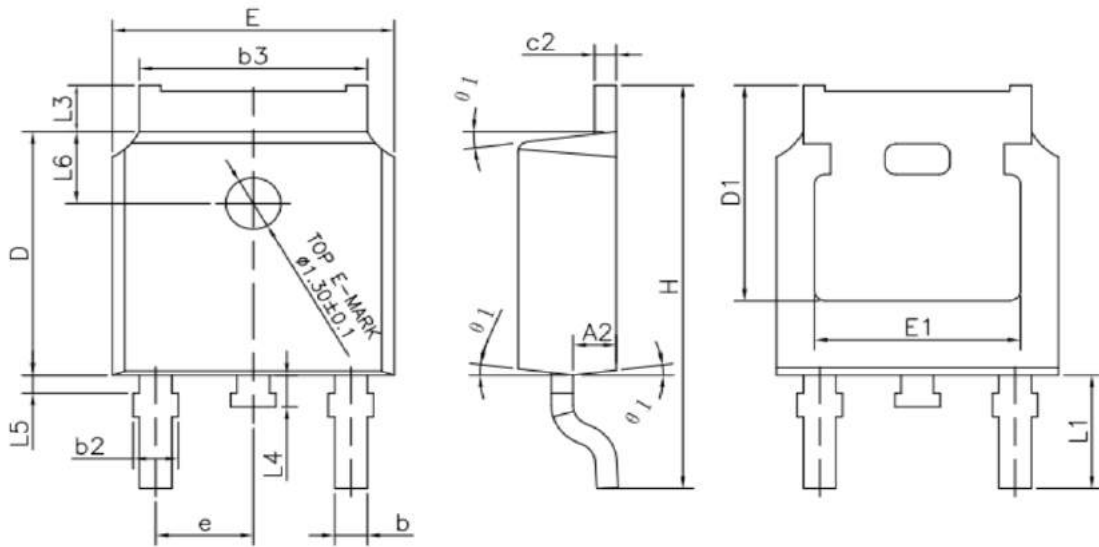
Fig C. Unclamped Inductive switching test circuit & waveform



\*.  $dv/dt$  controlled by  $R_G$   
\*.  $I_S$  controlled by pulse period

Fig D. Peak diode recovery  $dv/dt$  test circuit & waveform

## TO-252 Package Information



SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0	--	0.10
A2	0.90	1.01	1.10
b	0.72	--	0.85
b1	0.71	0.76	0.81
b2	0.72	--	0.90
b3	5.13	5.33	5.46
c	0.47	--	0.60
c1	0.46	0.51	0.56
c2	0.47	--	0.60
D	6.00	6.10	6.20
D1	5.25	--	--
E	6.50	6.60	6.70
E1	4.70	--	--
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.508 BSC		
L3	0.90	--	1.25
L4	0.60	0.80	1.00
L5	0.15	--	0.75
L6	1.80 REF		
$\theta$	0°	--	8°
$\theta_1$	5°	7°	9°
$\theta_2$	5°	7°	9°

## Customer Service

Sales and Service:

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